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### (54) SUBSTRATE PROCESSING SYSTEM, CONTROL DEVICE, AND SUBSTRATE TRANSFER PROCESSING METHOD

(71) Applicant: Tokyo Electron Limited, Tokyo (JP)

(72) Inventors: Minoru NAGASAWA, Tokyo (JP); Toshiharu HIRATA, Nirasaki City (JP); Takafumi MATSUHASHI,

Nirasaki City (JP)

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#### (57)ABSTRACT

A substrate processing system includes: one or more transfer modules configured to transfer substrates; a plurality of process modules configured to perform a substrate processing on the substrates transferred by the one or more transfer modules; and a control device configured to control the one or more transfer modules and the plurality of process modules, wherein the control device sequentially performs: calculating a substrate supply interval for supplying the substrates so that substrate transfer periods during which the substrates are transferred do not overlap with each other; and equalizing, based on the calculated substrate supply interval, a plurality of time intervals between the substrate transfer periods so that the substrate transfer periods are separated from each other.





